



Material Content Data Sheet



Halogen-Free

Sales Product Name	BTS50055-1TMB	Issued	17. February 2022
MA#	MA005698526		
Package	PG-TO220-7-11	Weight*	2125.63 mg

Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip_1	inorganic material	silicon	7440-21-3	13.394	0.63	0.63	6301	6301
chip_2	inorganic material	silicon	7440-21-3	2.120	0.10	0.10	997	997
leadframe	inorganic material	phosphorus	7723-14-0	0.272	0.01		128	
	non noble metal	iron	7439-89-6	0.908	0.04		427	
	non noble metal	copper	7440-50-8	906.793	42.66	42.71	426600	427155
wire	non noble metal	aluminium	7429-90-5	6.616	0.31	0.31	3113	3113
encapsulation	inorganic material	zinc oxide	1314-13-2	5.803	0.27		2730	
	miscellaneous	miscellaneous	-	23.213	1.09		10920	
	plastics	epoxy resin	-	87.047	4.10		40951	
	inorganic material	silicon dioxide	60676-86-0	464.250	21.84	27.30	218407	273008
lead finish	non noble metal	tin	7440-31-5	23.005	1.08	1.08	10823	10823
plating	inorganic material	phosphorus	7723-14-0	0.001			1	
	non noble metal	nickel	7440-02-0	0.216	0.01	0.01	101	102
solder	non noble metal	tin	7440-31-5	0.164	0.01		77	
	noble metal	silver	7440-22-4	0.205	0.01		96	
	non noble metal	lead	7439-92-1	7.820	0.37	0.39	3679	3852
glue	plastics	Polyimide	26023-21-2	0.217	0.01	0.01	102	102
heatspreader	inorganic material	phosphorus	7723-14-0	0.175	0.01		82	
	non noble metal	iron	7439-89-6	0.584	0.03		275	
	non noble metal	copper	7440-50-8	582.824	27.42	27.46	274190	274547
*deviation	< 10%	Sum in total:				100.00		1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
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3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and contains Pb according RoHS exemption 7a, Lead in high melting temperature type solders.

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